# **Equipment Information Sheet Resist Hot Strip Bath**

Manager: Giovanni Sartorello 607-254-4853 Calls to staff phones will be automatically forwarded to Backup: Garry Bordonaro 607-254-4936 Backup: Michael Skvarla 607-254-4674

## SAFETY

• Fire hazard - heated solvent (Propylene glycol, NMP, TMAH)

#### **USAGE RESTRICTIONS**

• No buddy system restrictions imposed on normal operation

#### SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 0 minutes

- No scheduling at this time
- Bath may be shared

## MATERIALS COMPATIBILITY CATEGORY

#### **Tool Category 5: Class A and B Metals and Compounds**

Allowed	Not Allowed
Tool category 1/1E, 2, 3, and 4 materials	
Silicon Based Substrates and Films	
III/V compound Semiconductors	
Glass Substrates	
PECVD and ALD Films	
Cured organics and baked Photoresist	
CNF Class A, B, and Refractory metals	
Exposed Gold, Silver, Copper	
Alkali and Alkaline Compounds	
Organic/Biology Molecules prepared- w/salt buffers	
High Vapor Pressure Materials (Mg, Ca, Zn)*	* Some tool restrictions on high vapor pressure materials may apply
Soft organic materials	

## High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

#### **Additional Material Restrictions and Exceptions**

- Resist coated substrates only NO lift-off processing
- NO SU-8, Polyimide, LOR, Class 2 Materials
- Holder must retain substrate no loose material

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their cell phones during accessible hours. At other times leave a message or send them an email.